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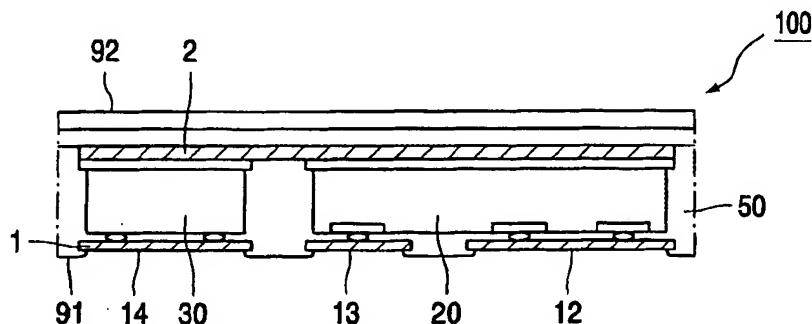
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[Continued on next page]

(54) Title: ELECTRONIC DEVICE AND METHOD OF MANUFACTURING SAME



(57) **Abstract:** The device of the invention comprises a semiconductor element, a first connection element, a first patterned electrically conductive layer and a second patterned electrically conductive layer. The device is further provided with an encapsulation that encapsulates all except the first conductive layer, which is part of the substrate. The device can be suitably made in that the second conductive layer is provided, in pre-patterned form, with a permeable isolating layer as a foil.



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